

# 5A, 20V - 200V Schottky Barrier Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Low power loss, high efficiency
- Ideal for automated placement
- Guard ring for overvoltage protection
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- Low voltage, high frequency
- DC/DC converter
- Freewheeling diodes
- Reverse battery protection
- Car lighting

## **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.210g (approximately)

KEY PARAMETERS						
PARAMETER	VALUE	UNIT				
l <sub>F</sub>	5	Α				
$V_{RRM}$	20 - 200	V				
I <sub>FSM</sub>	120	Α				
T <sub>J MAX</sub>	150 °C					
Package	DO-214AB (SMC)					
Configuration	Single die					









DO-214AB (SMC)



		SK	SK	SK	SK	SK	SK	SK	SK	SK	
PARAMETER	SYMBOL	52C	53C	54C	55C	56C	59C	510C	515C	520C	UNIT
		н	Н	Н	Н	Н	Н	Н	н	н	
Marking code on the device		SK 52C	SK 53C	SK 54C	SK 55C	SK 56C	SK 59C	SK 510C	SK 515C	SK 520C	
Repetitive peak reverse voltage	$V_{RRM}$	20	30	40	50	60	90	100	150	200	٧
Reverse voltage, total rms value	$V_{R(RMS)}$	14	21	28	35	42	63	70	105	140	٧
Forward current	I <sub>F</sub>	5						Α			
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	120						Α			
Critical rate of rise of off-state voltage	dV/dt	//dt 10,000						V/µs			
Junction temperature	$T_J$	- 55 to +150						°C			
Storage temperature	T <sub>STG</sub>	- 55 to +150					°C				



THERMAL PERFORMANCE							
PARAMETER	SYMBOL	TYP	UNIT				
Junction-to-lead thermal resistance	R <sub>OJL</sub>	17	°C/W				
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	50	°C/W				

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
	SK52CH SK53CH SK54CH		V <sub>F</sub>	-	0.55	V
Forward voltage <sup>(1)</sup>	SK55CH SK56CH	I <sub>F</sub> = 5A, T <sub>J</sub> = 25°C		-	0.75	٧
	SK59CH SK510CH			-	0.85	V
	SK515CH SK520CH			ı	0.95	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	SK52CH SK53CH SK54CH SK55CH SK56CH	T <sub>J</sub> = 25°C	I <sub>R</sub>	-	0.5	mA
	SK59CH SK510CH SK515CH SK520CH			-	0.3	mA
	SK52CH SK53CH SK54CH		I <sub>R</sub>	-	20	mA
	SK55CH SK56CH	T <sub>J</sub> = 100°C		-	10	mA
	SK59CH SK510CH SK515CH SK520CH			-	-	mA
	SK52CH SK53CH SK54CH		I <sub>R</sub>	-	-	mA
	SK55CH SK56CH	T <sub>J</sub> = 125°C		-	-	mA
	SK59CH SK510CH SK515CH SK520CH	, , , , , , , , , , , , , , , , , , ,		-	5	mA

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION						
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING				
SK5xCH	DO-214AB (SMC)	3,000 / Tape & Reel				

# Notes:

1. "x" defines voltage from 20V(SK52CH) to 200V(SK520CH)



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

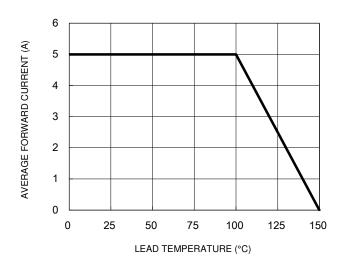


Fig.3 Typical Reverse Characteristics

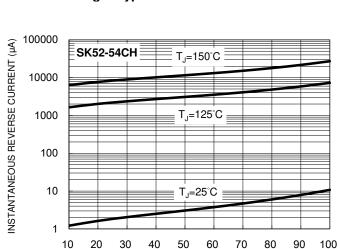


Fig.5 Typical Reverse Characteristics

PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

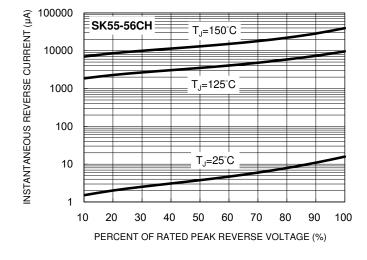


Fig.2 Typical Junction Capacitance

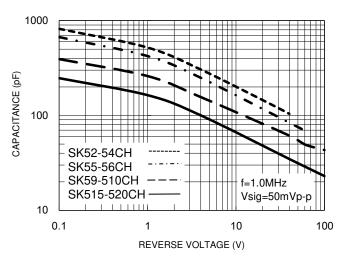
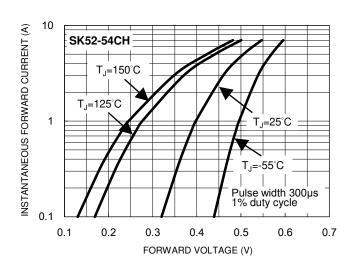
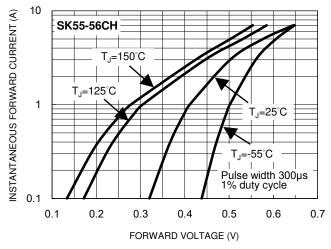


Fig.4 Typical Forward Characteristics



**Fig.6 Typical Forward Characteristics** 



Version: B2212

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## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.7 Typical Reverse Characteristics

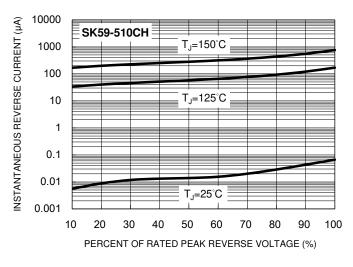
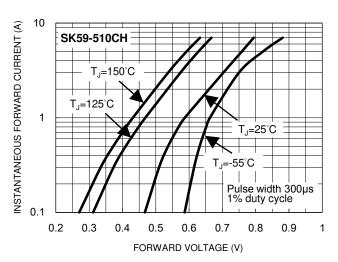
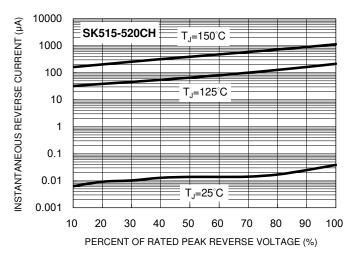


Fig.8 Typical Forward Characteristics



**Fig.9 Typical Reverse Characteristics** 





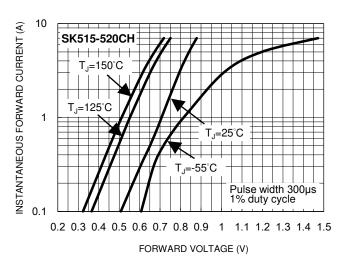
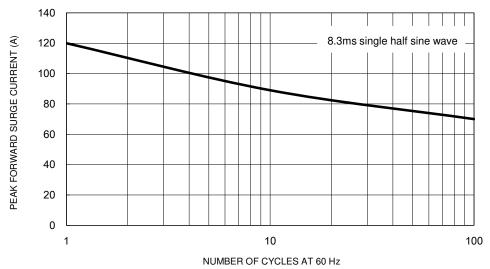


Fig.11 Maximum Non-Repetitive Forward Surge Current



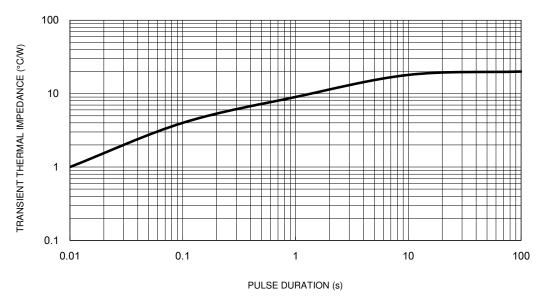
4



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

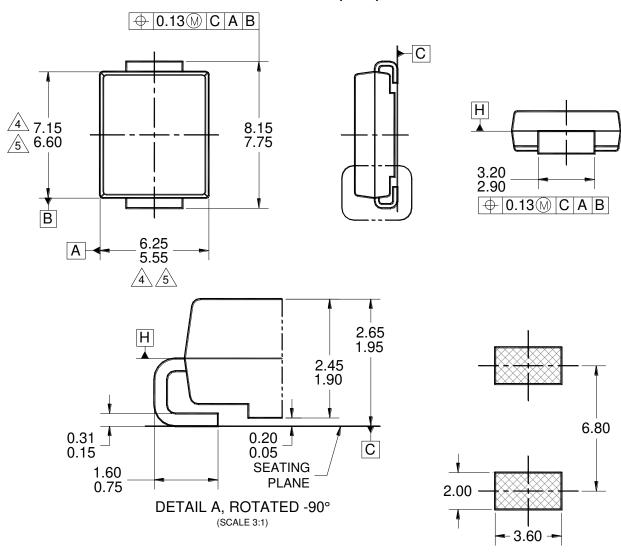
Fig.12 Typical Transient Thermal Characteristics

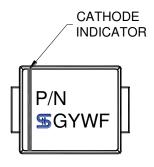




## **PACKAGE OUTLINE DIMENSIONS**

## **DO-214AB (SMC)**





## MARKING DIAGRAM

P/N = MARKING CODE

G = GREEN COMPOUND

YW = DATE CODE

F = FACTORY CODE

#### NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS ARE IN MILLIMETERS.

SUGGESTED PAD LAYOUT

- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC DO-214, VARIATION AB, ISSUE D.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
- MOLDED PLASTIC BODY LATERAL DIMENSIONS TO BE DETERMINED AT DATUM PLANE H.
- 6. DWG NO. REF: HQ2SD07-DO214SMC-036 REV A.



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